

Title (en)

METHOD FOR DEGREASING FORMED PRODUCT FROM POWDER

Title (de)

VERFAHREN ZUR BINDERENTFERNUNG BEI AUS PULVER GEFORMTEN KÖRPERN

Title (fr)

PROCEDE SERVANT A DEGRAISSER UN PRODUIT FABRIQUE A PARTIR DE POUDRE

Publication

EP 1375451 A4 20040811 (EN)

Application

EP 01949907 A 20010704

Priority

- JP 0105782 W 20010704
- JP 2000227269 A 20000727
- JP 2001079702 A 20010321

Abstract (en)

[origin: US2002182098A1] There is provided a method for debinding of powder molded body, which comprises dipping, in an extracting solution composed of an aqueous surfactant solution, a ceramic powder or metal powder molded body containing a binder comprising at least two kinds of binder components, to selectively extract and remove at least one kind of binder component from the molded body, and then removing the binder components remaining in the molded body after extraction. This debinding method enables a short time and rapid debinding treatment while preventing the generation of defects such as cracks and the like, has high safety to human health and environment, and requires a low facility cost.

IPC 1-7

C04B 35/638; **B22F 3/10**

IPC 8 full level

B22F 3/10 (2006.01); **C04B 35/638** (2006.01); **C04B 38/06** (2006.01)

CPC (source: EP US)

B22F 3/1025 (2013.01 - EP US); **C04B 35/624** (2013.01 - EP US); **C04B 35/62655** (2013.01 - EP US); **C04B 35/63** (2013.01 - EP US); **C04B 35/632** (2013.01 - EP US); **C04B 35/638** (2013.01 - EP US); **C04B 38/06** (2013.01 - EP US); **C04B 2235/449** (2013.01 - EP US)

Citation (search report)

- [X] PATENT ABSTRACTS OF JAPAN vol. 016, no. 464 (M - 1316) 28 September 1992 (1992-09-28)
- See references of WO 0210089A1

Cited by

CN102601371A; CN102601368A; CN102601370A; WO2007111633A3

Designated contracting state (EPC)

AT BE CH CY DE FR GB IT LI

DOCDB simple family (publication)

US 2002182098 A1 20021205; **US 6649106 B2 20031118**; AU 7101601 A 20020213; EP 1375451 A1 20040102; EP 1375451 A4 20040811; JP 2002104879 A 20020410; WO 0210089 A1 20020207

DOCDB simple family (application)

US 7055302 A 20020307; AU 7101601 A 20010704; EP 01949907 A 20010704; JP 0105782 W 20010704; JP 2001079702 A 20010321